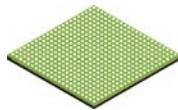


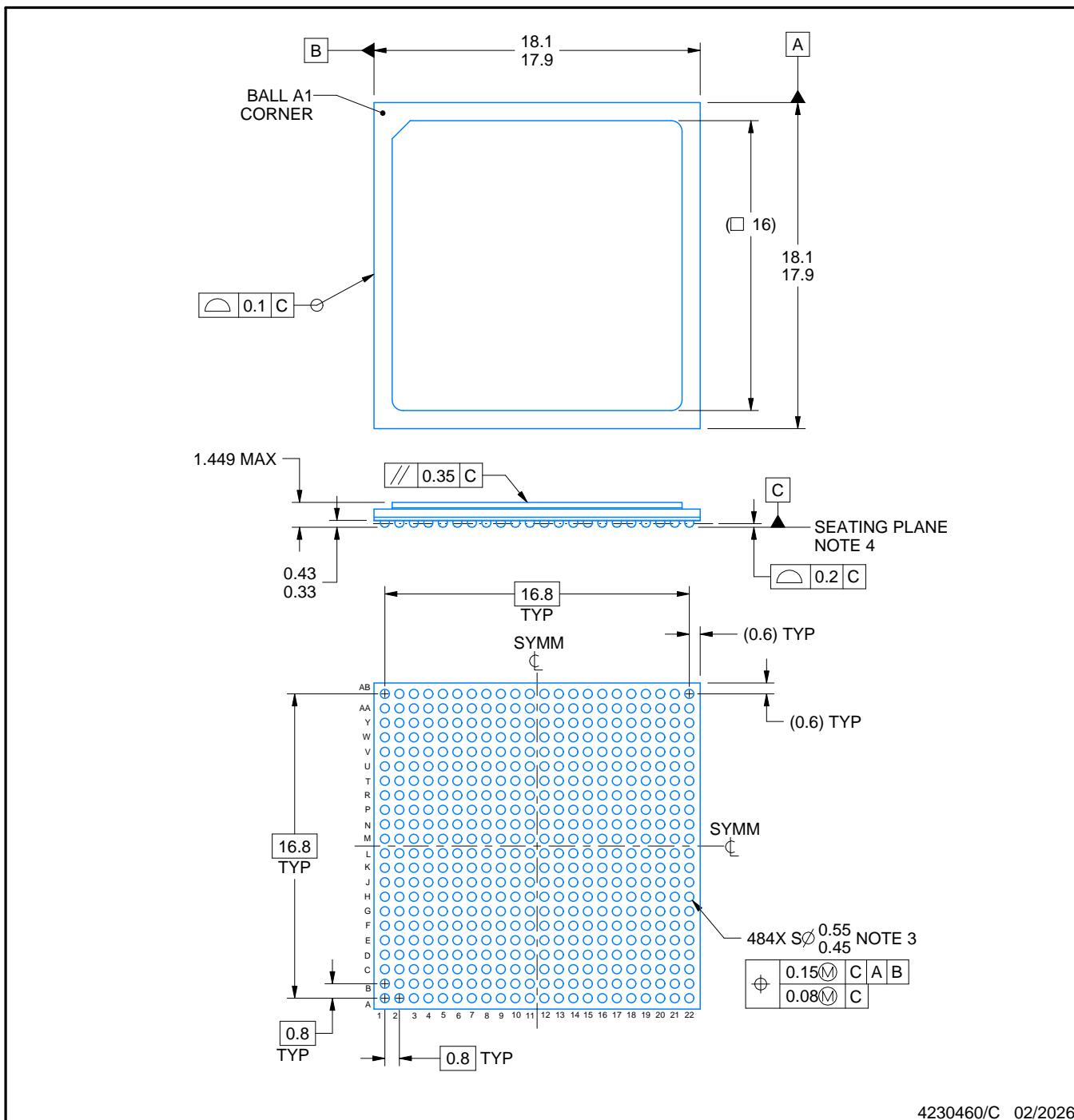
# PACKAGE OUTLINE

**ANF0484A**



**FCCSP - 1.449 mm max height**

BALL GRID ARRAY



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**NOTES:**

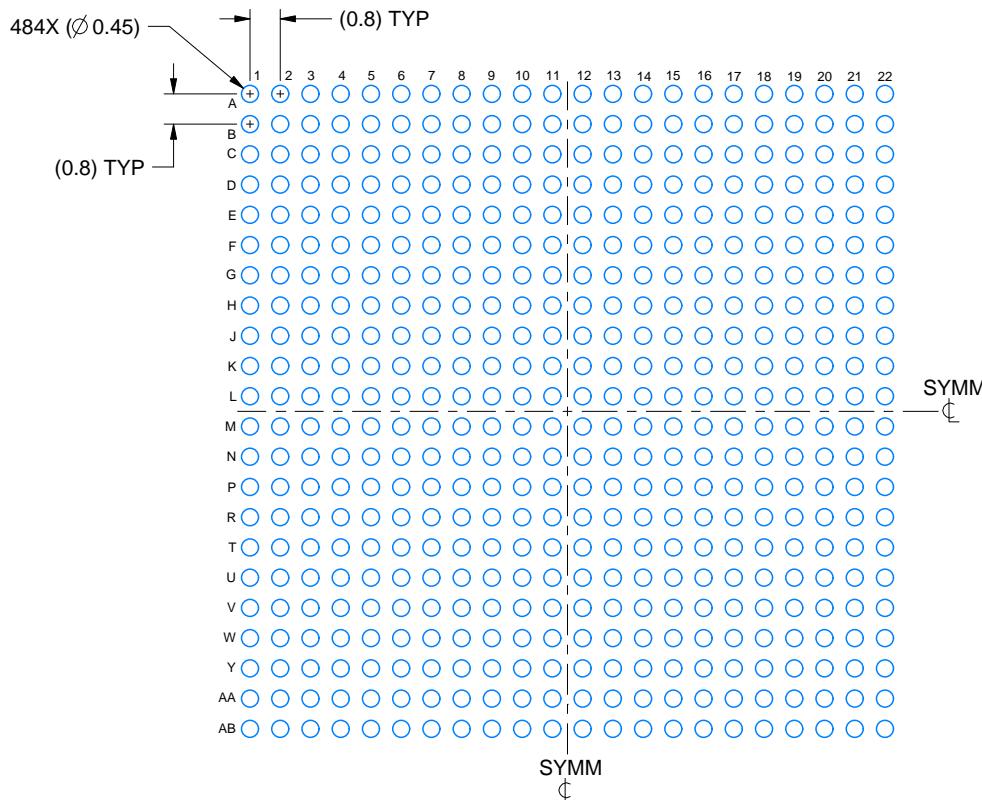
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Dimension is measured at the maximum solder ball diameter, post reflow, parallel to primary datum C.
4. Primary datum C and seating plane are defined by the spherical crowns of the solder balls.

# EXAMPLE BOARD LAYOUT

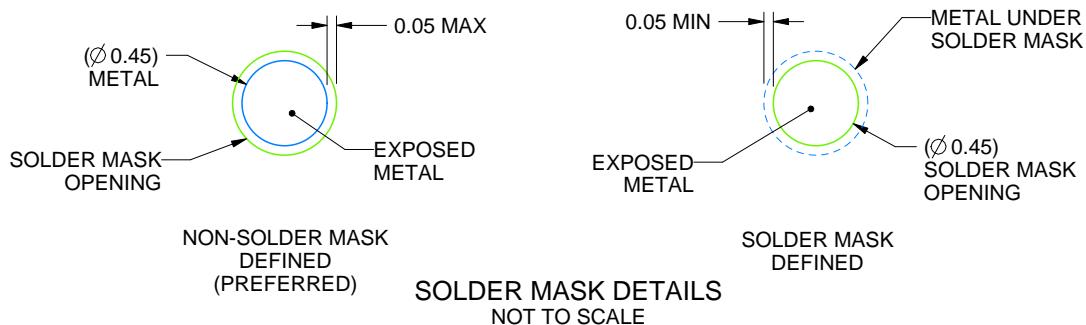
ANF0484A

FCCSP - 1.449 mm max height

BALL GRID ARRAY



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 5X



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NOTES: (continued)

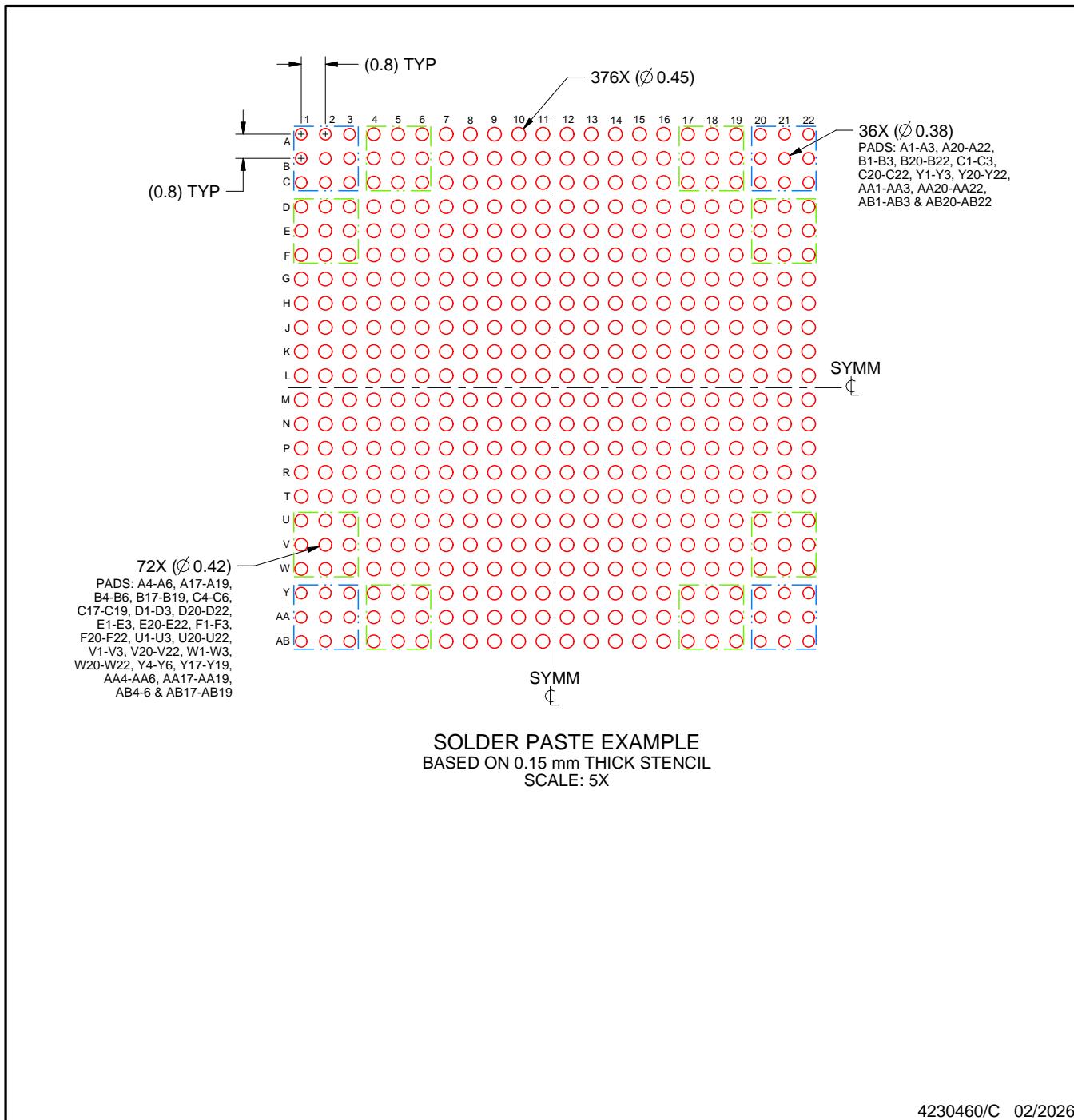
5. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints.  
See Texas Instruments Literature No. SPRU811 ([www.ti.com/lit/spru811](http://www.ti.com/lit/spru811)).

# EXAMPLE STENCIL DESIGN

**ANF0484A**

**FCCSP - 1.449 mm max height**

BALL GRID ARRAY



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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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